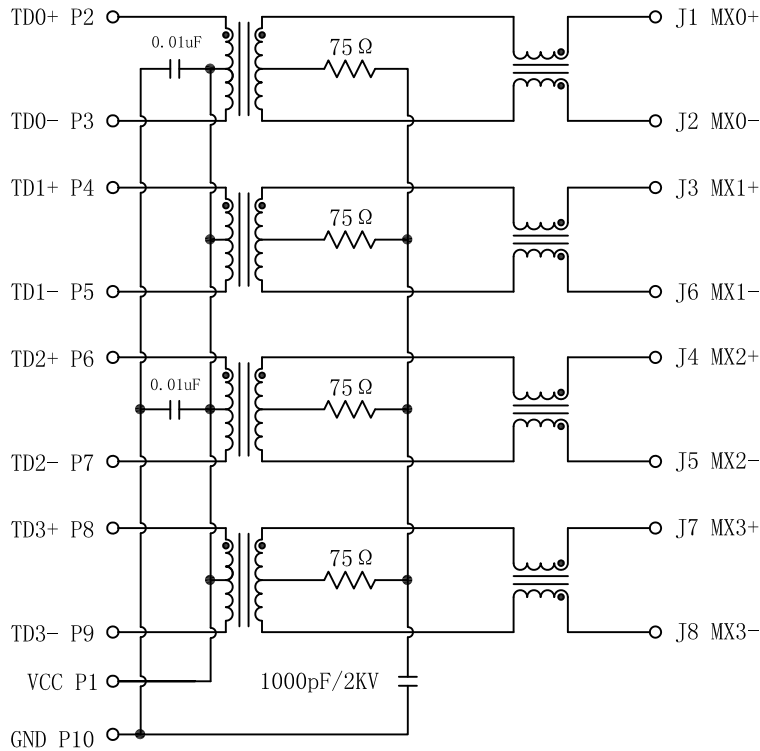


Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2015-06-26	

PCB CONNECTIONS



RJ45 CONNECTOR

ELECTRICAL SPECIFICATIONS @25°C

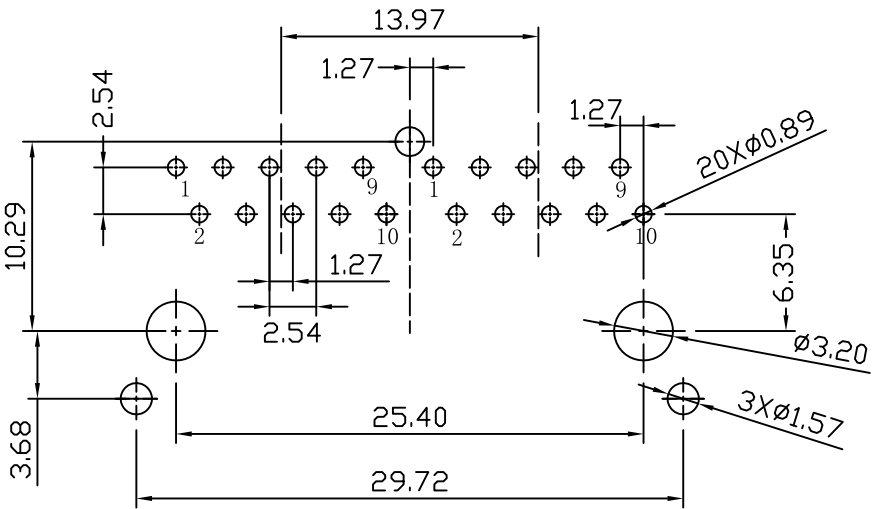
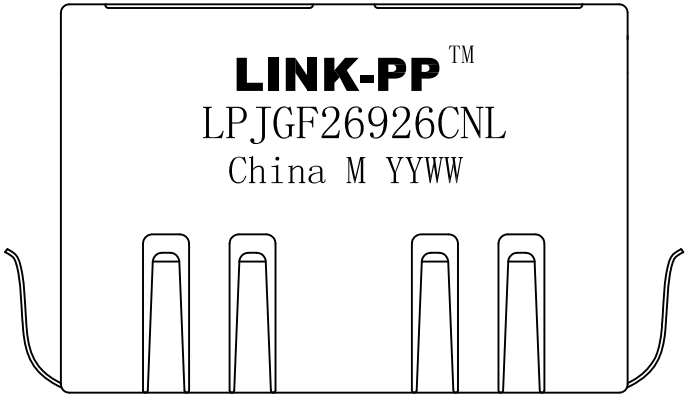
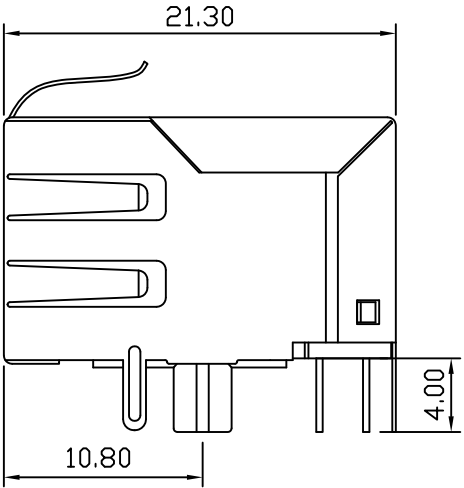
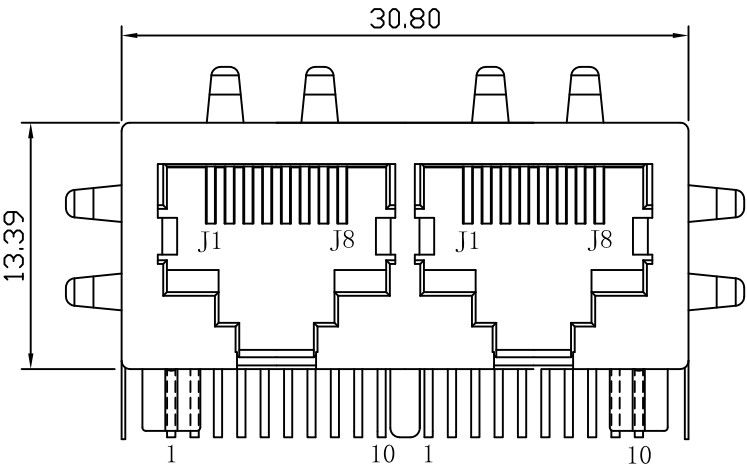
1. Turn Ratio($\pm 2\%$):
1CT:1CT
2. Inductance OCL:
350uH MIN@100KHz/0.1V,8mA DC Bias
3. DCR: 1.2 Ω MAX
4. Insertion Loss:
-1.0dB MAX @ 1-100MHz
5. Return Loss:
-18dB MIN @ 1-40MHz
-14dB MIN @ 60MHz
-12dB MIN @ 80MHz
-10dB MIN @ 100MHz
6. Cross talk:
-40dB MIN @ 1-30MHz
-35dB MIN @ 30-60MHz
-30dB MIN @ 60-100MHz
7. Common Mode Rejection:
-30dB MIN @ 1-50MHz
-20dB MIN @ 50-150MHz
8. Hipot: 1500Vrms MIN
9. Operating Temperature: -40°C TO +85°C



X:X	± 0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	± 0.25	CHKD:		
X:XXX	± 0.05	DR: TOM	TITLE: 1*2 RJ45 Connector with 1000 BASE-T Integrated Magnetics	
ANGLES	$\pm 1^\circ$	UNIT: mm	PART NO.: LPJGF26926CNL	
	SCALE: 2/1	SHEET: 1/2	REV: A	DWG NO.: LP15091402

Mechanical:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2015-06-26	



NOTES:

- 1.Meets IEEE 802.3 specification
- 2.Connector Materials:
Housing Material:Thermoplastic PA46+30%G.F UL94V-0
Contact Material:Phosphor Bonze C5210R-EH Thickness=0.35mm
Pins:Brass C2680R-H Thickness=0.35mm
Shield:SUS 201-1/2H Thickness=0.2mm
Contact plating: Gold 6 micro-inches min.In contact area.
- 3.Wave solder tip temperature: 265℃ Max, 5 Sec Max



X:X	±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	±0.25	CHKD:		
X:XXX	±0.05	DR: TOM	TITLE: 1*2 RJ45 Connector with 1000 BASE-T Integrated Magnetics	
ANGLES	±1°	UNIT: mm	PART NO.: LPJGF26926CNL	
	SCALE: 2/1	SHEET: 2/2	REV: A	DWG NO.: LP15091402